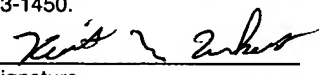


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	§	
Yau, et al.	§	
	§	Group Art Unit: Unknown
Serial No.: Unknown	§	
	§	
Confirmation No.: Unknown	§	
	§	Examiner: Unknown
Filed: HEREWITH	§	
	§	
For: A Low Dielectric Constant	§	
Film Produced From Silicon	§	
Compounds Comprising	§	
Silicon-Carbon Bond	§	

MAIL STOP PATENT APPLICATION
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:


CERTIFICATE UNDER 37 CFR 1.10	
I hereby certify that this correspondence and the documents referred to as attached therein are being deposited on <u>1/13</u> , 2004 with the United States Postal Service in an envelope as "Express Mail Post Office to Addressee," mailing label No. <u>EV335471697US</u> addressed to: MAIL STOP PATENT APPLICATION, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.	
<u>1/13/04</u> Date	 Signature

COMMENTS ON SUBMITTED REFERENCES

Applicants note that claim 1 of the instant application is within the scope of claim 1 of U.S. Patent No. 6,514,667, which is cited in the Information Disclosure Statement filed herewith. Applicants also note that the priority date of the instant application is prior to the priority date of U.S. Patent No. 6,514,667.

Applicants submit that the pending claims are patentable over the references of record and respectfully request allowance of the claims.

Respectfully submitted,



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Attorney for Applicant(s)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	§	
Yau, et al.	§	
	§	Group Art Unit: Unknown
Serial No.: Unknown	§	
	§	
Confirmation No.: Unknown	§	
	§	Examiner: Unknown
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For: A Low Dielectric Constant	§	
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<u>1/13/04</u> Date	<u>Ken [Signature]</u> Signature

INFORMATION DISCLOSURE STATEMENT

The Applicants, and the Attorney who signs below on the basis of the information supplied by the inventor and the information in his file, submit herewith patents, publications, or other information of which they are aware, which may be material to the examination of this application and in respect of which there may be a duty to disclose in accordance with 37 CFR § 1.56.

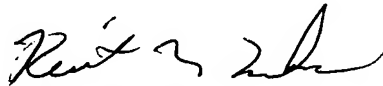
While the information submitted in this Information Disclosure Statement may be material pursuant to 37 CFR § 1.56, it is not intended to constitute an admission that any patent, publication, or other information referred to therein is prior art for this invention unless specifically designated as such.

In accordance with 37 CFR § 1.97, this Information Disclosure Statement is not to be construed as a representation that a search has been made or that no other possibly material information as defined under 37 CFR § 1.56(a) exists.

The patents and/or publications submitted herewith are set forth on the attached Form PTO-1449.

If the sum of \$180.00 is due under 37 CFR § 1.17(p) pursuant to § 1.97, the Commissioner is hereby authorized to charge this fee, and any other fee necessary to make this submission timely, to the Deposit Account No. 20-0782/AMAT/2592.C7/KMT.

Respectfully submitted,



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Attorney for Applicant(s)

U.S. Department of Commerce, Patent and Trademark Office				Docket No.		Serial No.	
(PTO Form 1449 modified)				AMAT/2592.C7/DSM/ LOW K/JW		UNKNOWN	
LIST OF PATENTS AND PUBLICATIONS CITED BY APPLICANT				Applicant YAU, et al.		Confirmation No.: UNKNOWN	
(Use several sheets if necessary)				Filing Date		Group	
Examiner UNKNOWN				HEREWITH		UNKNOWN	
U.S. Patent Documents							
Examiner Initial		Document Number	Issue Date	Applicant(s) Name	Class	Subclass	Filing Date If Appropriate
	A1	6,593,655	07/15/2003	Loboda, et al.	257	760	08/14/2000
	A2	6,514,667	02/04/2003	Angelopoulos, et al.	430	271.1	08/17/2001
	A3	6,316,167	11/13/2001	Angelopoulos, et al.	430	313	01/10/2000
	A4	6,287,990	09/11/2001	Cheung, et al.	438	780	09/29/1998
	A5	6,159,871	12/12/2000	Loboda, et al.	438	786	05/29/1998
	A6	6,147,009	11/14/2000	Grill et al.	438	780	06/29/1998
	A7	6,140,226	10/31/2000	Grill et al	438	637	07/30/1998
	A8	6,124,641	09/26/2000	Matsuura	257	759	12/08/1997
	A9	6,072,227	06/06/2000	Yau et al.	257	642	07/13/1998
	A10	6,068,884	05/30/2000	Rose, et al.	427	255.6	04/28/1998
	A11	6,054,379	04/25/2000	Yau, et al.	438	623	02/11/1998
	A12	6,054,206	04/25/2000	Mountsier	428	312.8	06/22/1998
	A13	6,051,321	04/18/2000	Lee, et al.	428	447	10/24/1997
	A14	5,989,998	11/23/1999	Sugahara, et al.	438	787	06/30/1997
	A15	5,946,593	08/31/1999	Saitoh	438	640	02/20/1996
	A16	5,891,799	04/06/1999	Tsui	438	624	08/18/1997
	A17	5,888,593	03/30/1999	Petrmichl, et al.	427	563	04/12/1996
	A18	5,874,367	02/23/1999	Dobson	438	787	06/30/1993
	A19	5,858,880	01/12/1999	Dobson, et al.	438	758	01/05/1996
	A20	5,834,162	11/10/1998	Malba	430	317	10/28/1996
	A21	5,821,168	10/13/1998	Jain	438	692	07/16/1997
	A22	5,817,572	10/06/1998	Chiang, et al.	438	624	12/18/1996
	A23	5,807,785	09/15/1998	Ravi	438	624	08/02/1996
	A24	5,800,877	09/01/1998	Maeda, et al.	427	535	08/09/1996
	A25	5,739,579	04/14/1998	Chiang, et al.	257	635	09/10/1996
	A26	5,753,364	05/19/1998	Rutherford, et al.	428	355R	01/30/1997
	A27	5,789,319	08/04/1998	Havemann, et al.	438	668	02/26/1996
	A28	5,703,404	12/30/1997	Matsuura	257	758	12/24/1996
	A29	5,700,720	12/23/1997	Hashimoto	438	622	12/20/1995
Examiner					Date Considered		
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.							

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(Use several sheets if necessary)					Filing Date		Group	
Examiner UNKNOWN					HEREWITH		UNKNOWN	
U.S. Patent Documents								
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	A30	5,698,901	12/16/1997	Endo	257	758	09/12/1995	
	A31	5,693,563	12/02/1997	Teong	438	627	07/15/1996	
	A32	5,683,940	11/04/1997	Yahiro	438	760	12/20/1995	
	A33	5,679,413	10/21/1997	Petrmichl, et al.	427	534	10/11/1996	
	A34	5,638,251	06/10/1997	Goel, et al.	361	313	10/03/1995	
	A35	5,637,351	06/10/1997	O'Neal, et al.	427	255.37	05/11/1995	
	A36	5,618,619	04/08/1997	Petrmichl, et al.	428	334	03/03/1994	
	A37	5,616,369	04/01/1997	Williams, et al.	427	536	06/24/1994	
	A38	5,599,740	02/04/1997	Jang, et al.	437	190	11/16/1995	
	A39	5,598,027	01/28/1997	Matsuura	257	635	12/21/1995	
	A40	5,593,741	01/14/1997	Ikeda	427	579	06/28/1995	
	A41	5,578,523	11/16/1996	Fiordalice, et al.	438	633	05/18/1995	
	A42	5,563,105	10/08/1996	Dubuzinsky, et al.	438	784	09/09/1994	
	A43	5,559,367	09/24/1996	Cohen, et al.	257	77	07/12/1994	
	A44	5,554,570	09/10/1996	Maeda, et al.	438	763	01/09/1995	
	A45	5,530,581	06/25/1996	Cogan	359	265	05/31/1995	
	A46	5,525,550	06/11/1996	Kato	437	238	11/19/1993	
	A47	5,508,368	04/16/1996	Knapp, et al.	427	534	03/03/1994	
	A48	5,494,712	02/27/1996	Hu, et al.	427	489	11/17/1994	
	A49	5,492,736	02/20/1996	Laxman, et al.	427	579	11/28/1994	
	A50	5,488,015	01/30/1996	Haveman, et al.	437	195	05/20/1994	
	A51	5,468,520	11/21/1995	Williams, et al.	427	560	06/24/1994	
	A52	5,465,680	11/14/1995	Loboda	117	84	07/01/1993	
	A53	5,364,666	11/15/1994	Williams, et al.	427	579	09/23/1993	
	A54	5,362,526	11/08/1994	Wang, et al.	427	573	01/23/1991	
	A55	5,360,646	11/01/1994	Morita	427	574	09/01/1993	
	A56	5,314,724	05/24/1994	Tsukune, et al.	427	489	08/27/1992	
	A57	5,298,587	03/29/1994	Hu, et al.	528	10	12/21/1992	
	A58	5,290,736	03/01/1994	Sato, et al.	437	238	09/24/1991	
Examiner					Date Considered			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.								

U.S. Department of Commerce, Patent and Trademark Office (PTO Form 1449 modified)					Docket No. AMAT/2592.C7/DSM/ LOW K/JW		Serial No. UNKNOWN	
LIST OF PATENTS AND PUBLICATIONS CITED BY APPLICANT					Applicant YAU, et al.		Confirmation No.: UNKNOWN	
(Use several sheets if necessary)					Filing Date HEREWITH		Group UNKNOWN	
Examiner UNKNOWN								
U.S. Patent Documents								
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	A59	5,284,730	02/08/1994	Takei, et al.	430	66	08/06/1992	
	A60	5,279,867	01/18/1994	Friedt, et al.	427	583	07/09/1992	
	A61	5,250,473	10/05/1993	Smits	438	790	08/02/1991	
	A62	5,246,887	09/21/1993	Yu	438	761	07/10/1991	
	A63	5,224,441	07/06/1993	Felts, et al.	118	718	09/27/1991	
	A64	5,208,069	05/04/1993	Clark, et al.	427	226	10/28/1991	
	A65	5,204,141	04/20/1993	Roberts, et al.	427	255.37	09/18/1991	
	A66	5,182,000	01/16/1993	Antonelli, et al.	204	181.1	11/12/1991	
	A67	5,156,881	10/20/1992	Okano, et al.	427	572	04/16/1991	
	A68	5,124,014	06/23/1992	Foo, et al.	438	694	04/11/1991	
	A69	5,120,680	06/09/1992	Foo, et al.	438	789	07/19/1990	
	A70	5,093,153	03/03/1992	Brochot, et al.	427	41	02/07/1989	
	A71	5,087,959	02/11/1992	Omori, et al.	257	635	03/02/1988	
	A72	5,040,046	08/13/1991	Chhabra, et al.	257	635	10/09/1990	
	A73	5,028,566	07/02/1991	Lagendijk	438	784	07/27/1990	
	A74	4,981,724	01/01/1991	Hochberg, et al.	427	255.37	10/28/1977	
	A75	4,973,511	11/27/1990	Farmer, et al.	428	216	12/01/1988	
Foreign Patent Documents								
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LIST OF PATENTS AND PUBLICATIONS CITED BY APPLICANT					Applicant YAU, et al.		Confirmation No.: UNKNOWN	
(Use several sheets if necessary)					Filing Date HEREWITH		Group UNKNOWN	
Examiner UNKNOWN								
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	A76	4,900,591	02/13/1990	Bennett, et al.	427	255.17	01/20/1988	
	A77	4,894,352	01/16/1990	Lane, et al.	438	763	10/26/1988	
	A78	4,845,054	07/04/1989	Mitchener	438	790	06/26/1987	
	A79	4,842,888	06/27/1989	Haluska, et al.	427	38	04/07/1988	
	A80	4,828,880	05/09/1989	Jenkins, et al.	427	167	12/21/1987	
	A81	4,824,690	04/25/1989	Heinecke, et al.	427	39	11/03/1987	
	A82	4,812,325	03/14/1989	Ishihara, et al.	427	69	10/21/1986	
	A83	4,798,629	01/17/1989	Wood, et al.	106	287.16	10/22/1987	
	A84	4,789,648	12/06/1988	Chow, et al.	438	633	10/28/1985	
	A85	4,557,946	12/10/1985	Sacher, et al.	427	489	06/03/1983	
	A86	4,168,330	09/18/1979	Kaganowicz	427	39	10/13/1977	
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	B48	0 840 365	05/06/1998	EP	H01L	21/311	<input type="checkbox"/>	<input checked="" type="checkbox"/>
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(Use several sheets if necessary)		Filing Date	Group
Examiner UNKNOWN		HEREWITH	UNKNOWN
OTHER ART			
Examiner Initial		Including Author, Title, Date, Pertinent Pages, Etc.	
	C1	Y.S. Lin, et al. "Plasma Polymerization of Trimethylsilane in Cascade Arc Discharge" Department of Chemical Engineering, and Center for Surface Science and Plasma Technology, University of Missouri-Columbia, 4 February 1997, pg 1653-1665.	
	C2	W. D. Brown "Dielectric Material Integration for Microelectronics" Dielectric Science and Technology and Electronics Divisions Proceedings Volume 98-3, 8 pages.	
	C3	A. Grill, et al. "Diamondlike Carbon Materials as Low-k Dielectrics" 1997 Materials Research Society, pages 417-423.	
	C4	A.M. Wrobel, et al. "Reactivity of Alkylsilanes and Alkylcarbosilanes in Atomic Hydrogen-Induced Chemical Vapor Deposition" Polish Academy of Sciences, Centre of Molecular and Macromolecular Studies, 90-363 Lodz, Poland, pages 1060-1065.	
	C5	Laura Peters "Pursuing the Perfect Low-K Dielectric" 64 Semiconductor International, September 1998, 7 pages.	
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